



2814
PATENT
29926/37833

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Hyung-Bok Choi

I hereby certify that this paper and the documents referred to as enclosed therewith are being deposited with the United States Postal Service as first class mail, postage prepaid, on October 16, 2002, in an envelope addressed to Commissioner for Patents, Washington, D.C. 20231.

[Handwritten signature over the text]

Michael R. Hull
Reg. No. 35,902
Attorney for Applicant

[Handwritten signatures and initials: 'g/a', 'G. S. [initials]', and '10-20-02' are visible on the right side of the page.]

Serial No.: 10/054,528

Filed: January 22, 2002

For: Semiconductor Device and
Method of Fabricating the Same

Group Art Unit: 2814

Examiner:

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the office action mailed on August 5, 2002, please amend the above-identified patent application, as follows:

In the Specification:

Please replace the paragraph beginning on page 10, line 1, with the following rewritten paragraph:

a1
-- Then the capacitor sacrificial film 47 is etched until the surface of the seed separating layer 45 is exposed. Thus, the portions of the seed layer 46 where the lower electrode 50 has not been deposited are exposed. Then the exposed portions of the seed layer 46 are removed by etching. Under this condition, the seed layer 46 is separated into a plurality of parts, and therefore, the lower electrode 50 is also separated into a plurality of parts between adjacent cells. Further, as shown in Fig. 3C, part of the seed layer 46 disposed beneath the electrode 50 still covers an inner portion of the seed separating layer 45 that encircles the connecting part 44.--

Please replace the paragraph beginning on page 10, line 19, with the following rewritten paragraph:

OCT 22 2002
TECHNOLOGY CENTER 2230

RECEIVED